

CHARACTERISTICS

Panel Dimension :	TBD
Board Dimension :	30.00 x 50.95 mm
Material :	FR4 150 Tg
PCB Thickness :	1.00 mm
Layers :	4
Copper Thickness :	Outer 35μ / Inner 35μ
Gap Min / Track Min :	150μ / 150μ
Copper Finish :	Chemical Ni/Au
Silkscreen :	Top & Bot (White)
Solder Mask :	Top & Bot (Green)
Electrical Test :	Yes
Control Impedance :	Yes (cf Stack-up below)
UL Marking :	Yes

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IMPEDANCE (IS400 / Er : 4.3)
TOP-IL1 / Single Ended : 50Ω / W : 210μ (Microstrip)
TOP-IL1 / Zdiff : 90Ω / W : 180μ / S : 190μ (Edge Coupled External)
IL2-BOT / Zdiff : 90Ω / W : 180μ / S : 190μ (Edge Coupled External)

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PCB STACK-UP
TOP
TSS-00008-X01.gbr / Top SilkScreen
TSM-00008-X01.gbr / Top Solder Mask
TOP-00008-X01.gbr / Top Layer / Copper 35μ
Isolation 0.12 mm - FR4
IL1-00008-X01.gbr / Int. Layer 1 / Copper 35μ
Isolation 0.71 mm - FR4
IL2-00008-X01.gbr / Int. Layer 2 / Copper 35μ
Isolation 0.12 mm - FR4
BOT-00008-X01.gbr / Bottom Layer / Copper 35μ
BSM-00008-X01.gbr / Bottom Solder Mask
Without Bottom SilkScreen
BOTTOM

